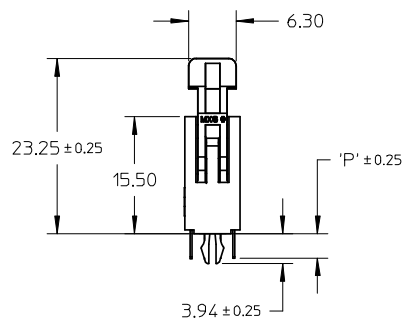
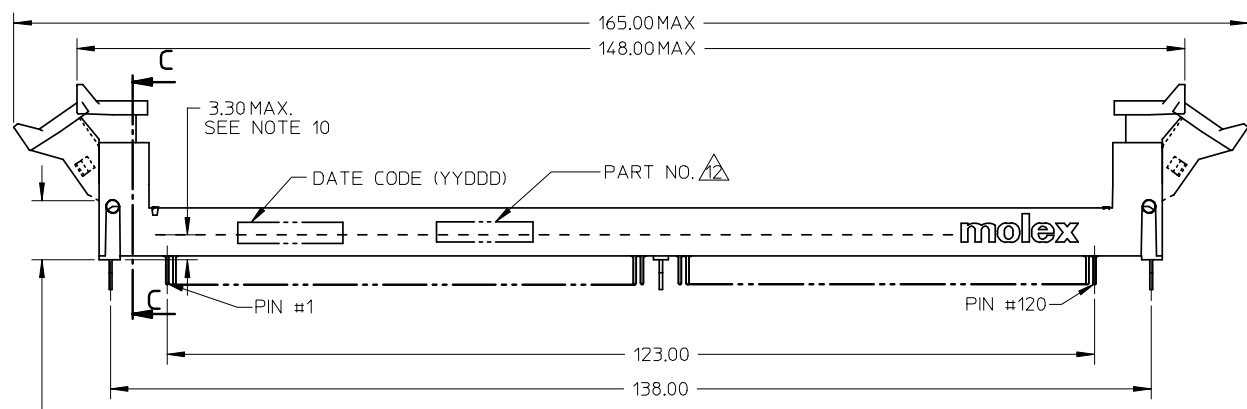
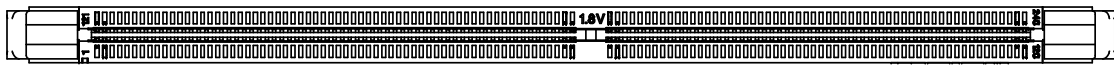


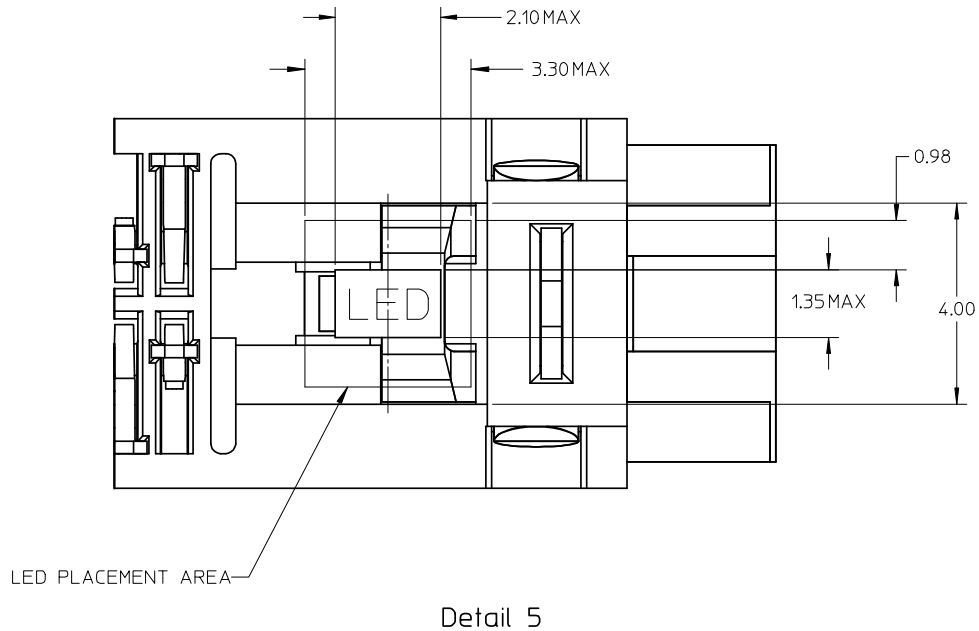
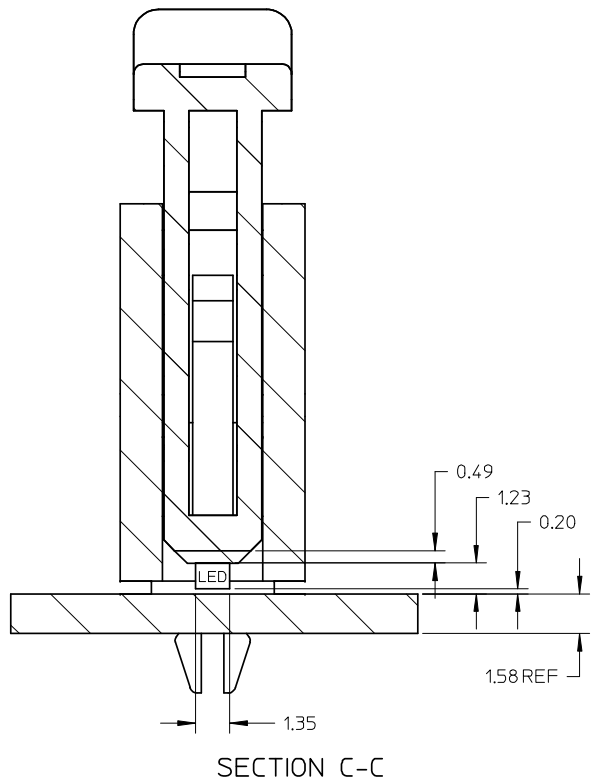
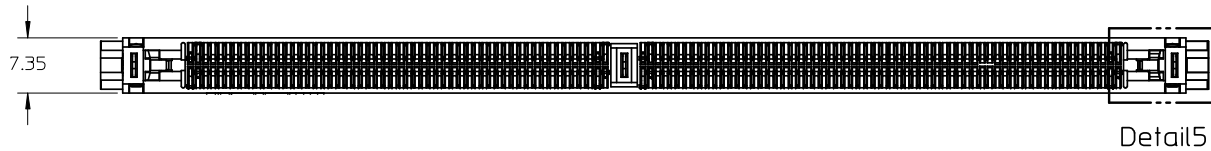
- NOTES:
- MATERIALS
 HOUSING - HIGH TEMP. NYLON GLASS FILLED, UL 94V-0
 COLOR: BLACK
 EJECTOR - HIGH TEMP. NYLON GLASS FILLED, UL 94V-0
 COLOR: SEE TABLE
 TERMINAL - COPPER ALLOY
 - PLATING - SEE TABLE IN SHEET 5 & 6.
 - CARD SLOT ACCEPTS 1.27±0.10 MM MODULE THICKNESS.
 (MEASURED OVER P.C. PADS)
 - RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-237.
 - REFER TO PRODUCT SPEC. PS-87705-002 FOR PERFORMANCE SPECIFICATIONS.
 - PRODUCT SHALL BE PACKED IN TRAY.
 - PRODUCT SHALL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.
 - KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS MOUNTED ONTO THE PCB WHICH DOES NOT INCLUDE THE LATCH.
 - REFER TO CRITICAL JEDEC INFORMATION FOR SOCKET OUTLINE PER SO-001.
 - DIMM MODULE SEATING PLANE FROM TOP OF PCB.
 - CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.
 - PART NUMBER SHALL BE MARKED LEGIBLY AS 87705-****



5.00 MIN
LATCH KEEP
OUT AREA

ADD NOTE @SHT4 C1 EC NO: S2008-1044 DRWN:CMTEO 2008/05/15 CHKD:CGTAN 2008/05/15 APPR:SHLENI 2008/05/15	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	CGOH	2002/05/09	DDR2 DIMM, 100MM PITCH			
		3 PLACES	± ---	± ---	CHECKED BY	DATE	240 CKTS			
	2 PLACES	± 0.20	± ---	DSOH	2002/07/22	(FORKLOCK VERSION)				
	1 PLACE	± ---	± ---	APPROVED BY	DATE	MOLEX INCORPORATED				
	ANGULAR ± 5 °			SKTOH	2002/07/23	DOCUMENT NO.				
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO.		SEE TABLE		SD-87705-001		
				SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
D1	REV			A3	SHEET NO. 1 OF 6					

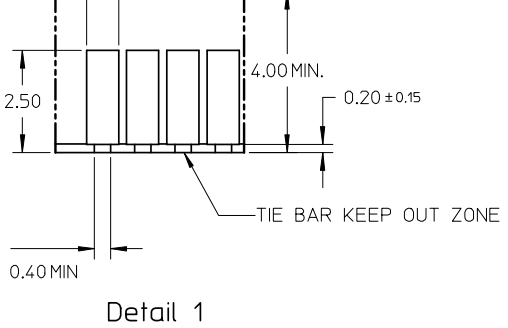
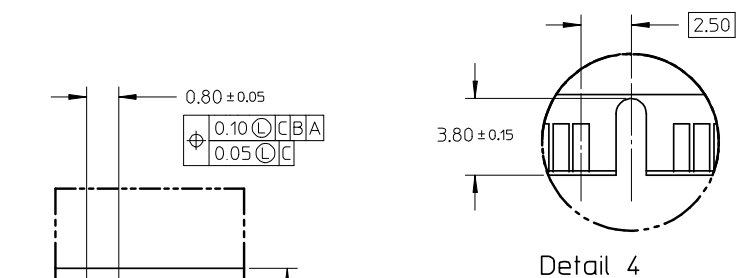
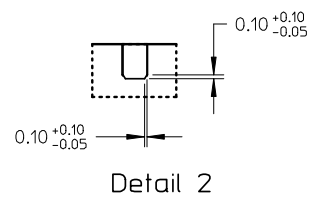
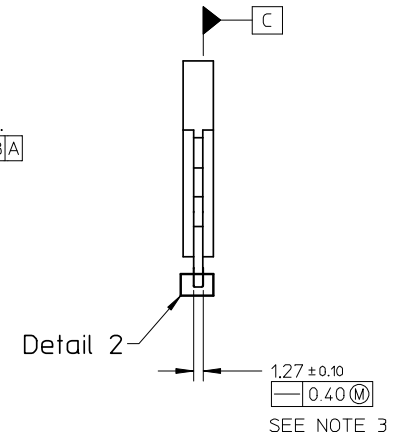
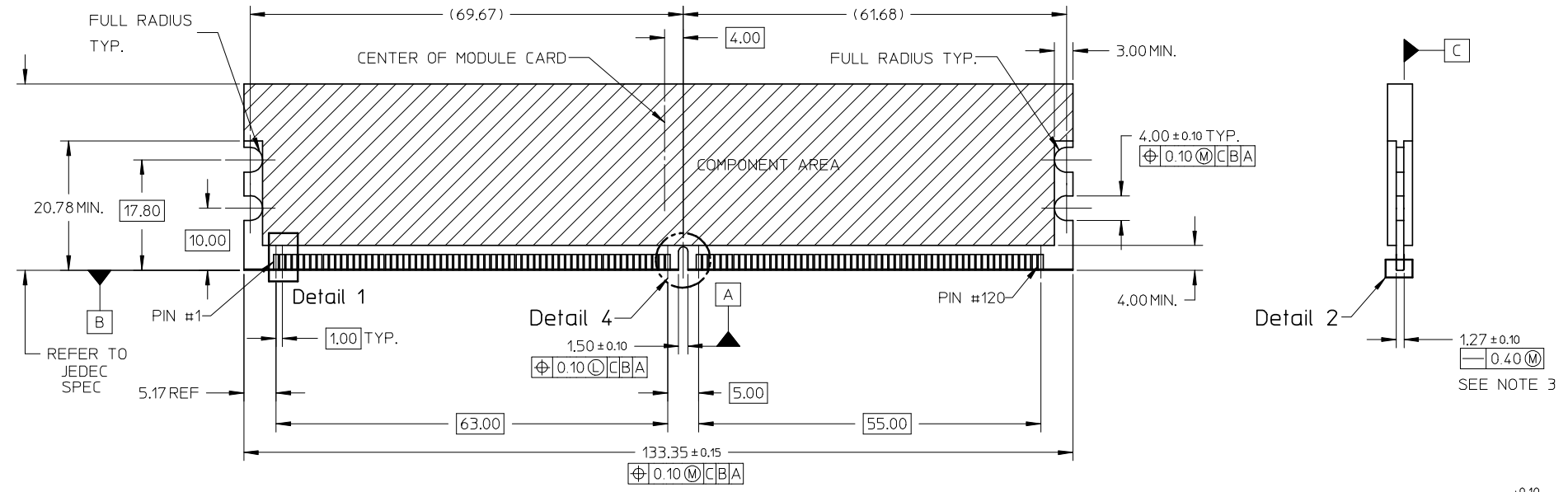
10 9 8 7 6 5 4 3 2 1



ADD NOTE @SHT 4 C1 EC NO: S2008-1044 DRW:CMTEO 2008/05/15 CHKD:CGTAN 2008/05/15 APPR:SHLENI 2008/05/15	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		▽=0 ◻=0	mm	INCH	DRAWN BY CGOH	DATE 2002/05/09	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)				
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.20 ± ---	1 PLACE ± --- ± ---	CHECKED BY DSOH	DATE 2002/07/22	MOLEX INCORPORATED			
		ANGULAR ± 5 °			APPROVED BY SKTOH		DATE 2002/07/23	DOCUMENT NO. SD-87705-001	SHEET NO. 2 OF 6		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

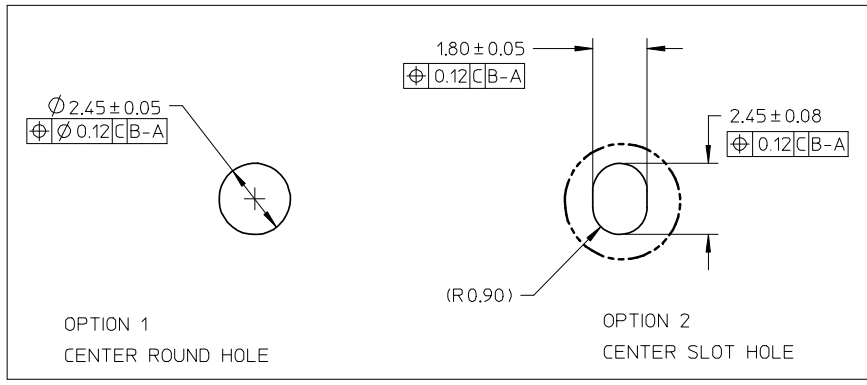
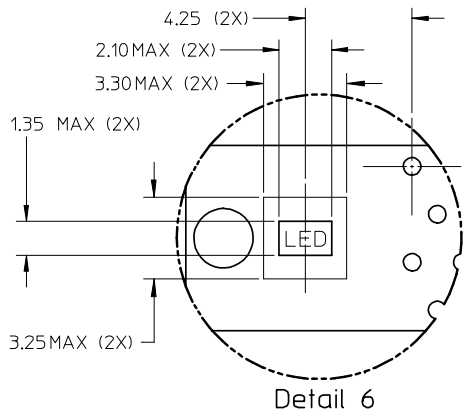
9 8 7 6 5 4 3 2 1

RECOMMENDED MODULE LAYOUT

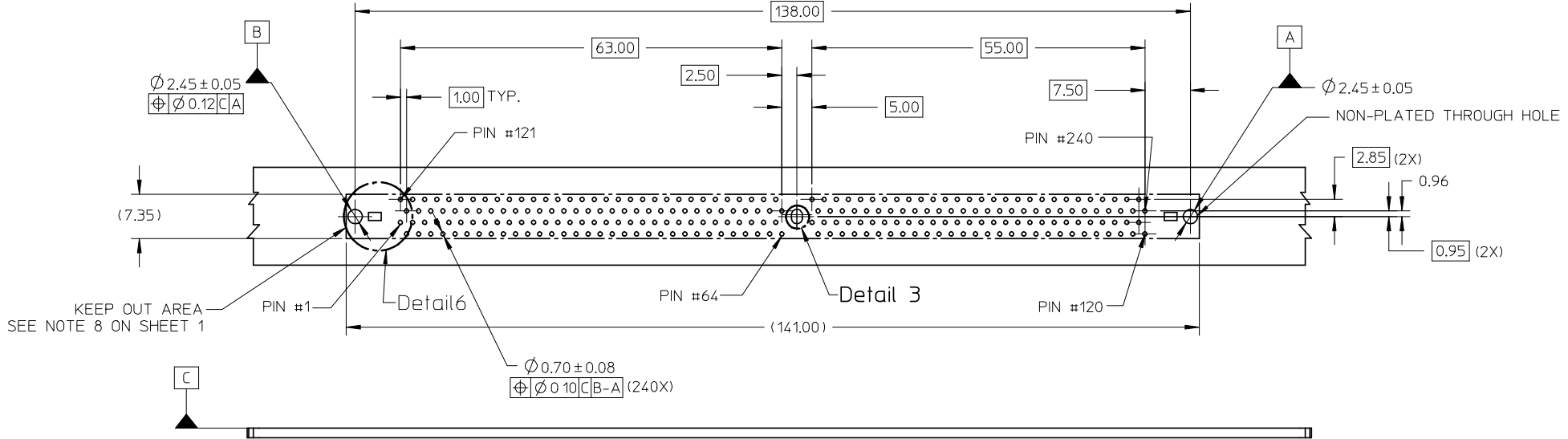


NOTES:
1. MODULE CARD USED FOR TESTS ARE WITH 0.10MM CHAMFER.

ADD NOTE @SHT4 C1 EC NO: S2008-1044 DRWN:CMTEO 2008/05/15 CHKD:CGTAN 2008/05/15 APPR: SILENI 2008/05/15	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	CGOH	2002/05/09	DDR2 DIMM, 100MM PITCH			
		3 PLACES	± ---	± ---	CHECKED BY	DATE	240 CKTS			
						MOLEX INCORPORATED				
						SD-87705-001				
						3 OF 6				
						SEE TABLE				
						THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



(SEE RECOMMENDED THICKNESS IN TABLE)
RECOMMENDED PCB LAYOUT
CONNECTOR SIDE



ADD NOTE @SHT 4 C1
EC NO: S2008-1044
DRW:CMTEO 2008/05/15
CHKD:CGTAN 2008/05/15
APPR:SHLENI 2008/05/15

QUALITY SYMBOLS	DESCRIPTION
$\blacktriangledown = 0$	
$\triangleleft = 0$	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± ---	± ---
3 PLACES ± ---	± ---
2 PLACES ± 0.20	± ---
1 PLACE ± ---	± ---
ANGULAR ± 5 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	



DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
CGOH	2002/05/09
CHECKED BY	DATE
DSOH	2002/07/22
APPROVED BY	DATE
SKTOH	2002/07/23
MATERIAL NO.	
SEE TABLE	

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	
TITLE		
DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)		
MOLEX INCORPORATED		
DOCUMENT NO.		SHEET NO.
SD-87705-001		4 OF 6
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	LATCH COLOR
87705-0021	CENTER (1.8V)	2.67	1.57	0.38µM / 15 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	NATURAL
87705-1021		3.18	2.36		
87705-1053		3.66			
87705-0031		2.67	1.57	0.03µM / 1 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	
87705-1031		3.18	2.36		
87705-0051		2.67	1.57	0.76µM / 30 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	
87705-1051		3.18	2.36		

ADD NOTE @SHT 4 C1 EC NO: S2008-1044 DRWN:CMTEO 2008/05/15 CHKD:CGTAN 2008/05/15 APPR:SHLENI 2008/05/15	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		=0 =0	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	DRAWN BY CGOH DATE 2002/05/09 CHECKED BY DS0H DATE 2002/07/22 APPROVED BY SKTOH DATE 2002/07/23	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-87705-001	SHEET NO. 5 OF 6	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	LATCH COLOR
87705-5051	CENTER (1.8V)	2.67	1.57	0.76µM / 30 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	CLEAR
87705-5151		3.18	2.36		
87705-6151		3.18	2.36	0.38µM / 15 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	
87705-9101		2.67	1.57	0.38µM / 15 µIN MIN. GOLD ON CONTACT, 2.54µM/ 100µIN MIN. TIN ON SOLDERTAILS, 1.27µM/ 50µIN MIN. NICKEL UNDERPLATE	

ADD NOTE @SHT 4 C1 EC NO: S2008-1044 DRWN:CMTEO 2008/05/15 CHKD:CGTAN 2008/05/15 APPR:SHLENI 2008/05/15	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		 = 0  = 0	mm INCH	MM ONLY	NTS	METRIC	DRAWN BY: CGOH DATE: 2002/05/09 CHECKED BY: DS0H DATE: 2002/07/22 APPROVED BY: SKTOH DATE: 2002/07/23 MATERIAL NO. SEE TABLE DOCUMENT NO. SD-87705-001 SHEET NO. 6 OF 6
		4 PLACES ± --- ± ---	± --- ± ---	DRAWN BY DATE	TITLE		
		3 PLACES ± --- ± ---	± --- ± ---	CHECKED BY DATE	DDR2 DIMM, 100MM PITCH 240 CKTS (FORKLOCK VERSION)		
2 PLACES ± 0.20 ± ---	± --- ± ---	APPROVED BY DATE	MOLEX INCORPORATED				
1 PLACE ± --- ± ---	± --- ± ---	ANGULAR ± 5 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			